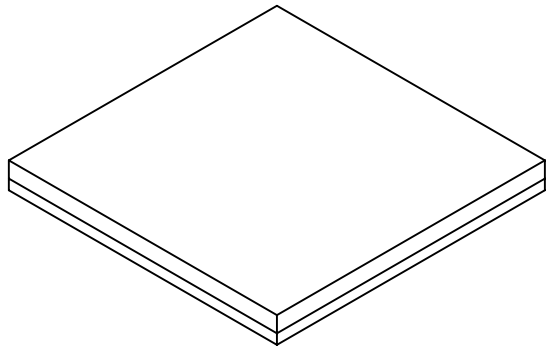
02	UPDATED TOLERANCES PER DCN C04738	10/02/98	E.B.	HLE



REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.

PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 40.

THE MAXIMUM SOLDER BALL MATRIX SIZE IS 8 X 8.

THE BASIC SOLDER BALL GRID PITCH IS 0.50.

ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

3: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

DECIMAL	ANGULAR
X.X ±0.10	±1°
X.XX ±0.05	
X.XXX ±0.03	

MATERIAL: N/A

FINISH: N/A

DO NOT SCALE DRAWING

PROJECTION

APPROVALS	DATE
DRAWN D. BIGGS	01/20/98
CHECKED D. GASTELUM	01/20/98
ENG'R T. PANCZAK	01/20/98
RELEASED M. ANTONIO	01/22/98

ANAM Industrial Co., LTD. Sungdong-Ku, Seoul, Korea

AMKOR Electronics, Inc. Chandler, Arizona, USA

amkor anam

TITLE: PACKAGE OUTLINE – CABGA 40, 5.00mm X 5.00mm, 2 LAYER, 0.50mm PITCH, LAMINATE SUBSTRATE, AAP

SIZE	SID NUMBER	DWG NUMBER	REV
B	N/A	73349	02

STRIP DWG NUMBER/REV	CUST CODE	SCALE	SHEET
N/A	N/A	SCALE: 8:1	SHEET 1 OF 3

7 6 5 4 3 2 1

E D C B A